PCN Number:		ımber:	20190129003.0			PCN Date:	Ja	January 30, 2019				
Title: Datasheet for UCC256303												
Customer Contact:			PCN Manage		Dept:			Quality Services				
Ch		е Туре:										
Assembly Site					Design				Wafer	· Bump Site		
Assembly Process										Bump Material		
Assembly Materials					Part number change					Bump Process		
Mechanical Specification					Test Site					Fab Site		
Packing/Shipping/Labeling					Test Process			<u> </u>		Wafer Fab Materials		
									water	Fab Process		
Notification Details												
Description of Change: Texas Instruments Incorporated is announcing an information only notification.												
The product datasheet(s) is being updated as summarized below. The following change history provides further details.												
SLUSD49A – SEPTEMBER 2017–REVISED JANUARY 2019												
Changes from Revision Original (September 2017) to Revision A Page												
Added a footnote for VCC absolute maximum rating												
The datasheet number will be changing.												
Device Family							Change From:			Change To:		
UCC256303							SLUSD49			SLUSD49A		
The	ese c	hanges may be	reviewed at	the	e datasheet	links provide	d.					
http://www.ti.com/product/UCC256303												
Reason for Change:												
То	accu	rately reflect de	evice charact	eris	stics.							
An	ticip	ated impact o	n Fit, Form	, Fi	unction, Q	uality or Rel	iab	ilit	y (posi	tive / negative):		
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.												
Changes to product identification resulting from this PCN:												
None.												
Product Affected:												
_		630-3DDBR	UCC256	30-	3DDBT							
For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.												

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com